# Corresponding to RoHS Directive

		Conductive Polymer Aluminum Solid Electrolytic Capacitors				Conductive Polymer Aluminum Solid Electrolytic Capacitors(FPCAP)	
		SMD type (CV, CX, CR series)	Lead wire terminal type (LV, LX series)	SMD type (except CV, CX, CR)	Lead wire terminal type (except LV, LX)	SMD type	Lead wire terminal type
Correspondir	ng to RoHS Directive	Complied				Complied	
Material	The portion of the components		· · · · · · · · · · · · · · · · · · ·				
Lead (Pb)	Plating on terminals	Sn p	lating	Ag plating		Sn plating	Sn plating
	Insulating Sleeves		Does no	t contain		Does not contain	
	Construction of terminals	Fe/Cu/Sn		Fe/Cu/Ag or Cu/Ag		Cu/Sn	Cu/Sn or Fe/Cu/Sn
	Resistance to soldering heat	Please refer to page 19 for the recommendation reflow condition.	Correspondence to 265°C flow soldering condition	Please refer to page 19 for the recommendation reflow condition.	Correspondence to 265°C flow soldering condition	Please refer to page 25 for the recommendation reflow condition(FPCAP).	Correspondence to 260°C flow soldering condition
	Solderability Tensile strength	No significant solderability difference between Sn-Ag-Cu and Sn-Pb solder.				No significant solderability difference between Sn-Ag-Cu and Sn-Pb solder.	
Chromium (VI)	Plating material		Does not contain			Does not contain	
Mercury							
Cadmium			Doos no	t contain		Deep not contain	
PBB		Does not contain					
PBDE							
Identification for RoHS compliance parts		Add "Pb free" marking on outer carton label				Add "Pb free" marking on outer carton label	
MSL (IPC/JEDEC J-STD-020D)		Not Applicable				Not Applicable	

		SMD type	Lead wire terminal type	Snap-in terminal type	Screw terminal type			
Corresponding to RoHS Directive		Corr	plied	Complied (Lug terminal type : Avallable)	Complied			
Material	The portion of the components							
Lead (Pb)	Plating on terminals	(< or=Dia.10mm) Change plating from Sn-Pb toSn-Bi	Change plating from Sn-Pb to Sn		AI			
		(> or=Dia.12.5mm) Change plating from Sn-Pb to Sn						
	Insulating Sleeves	No used	Replaced with PET		—			
	Construction of terminals	Fe/Cu/Sn-1.5Bi ( <or=dia 10mm)<="" td=""><td colspan="2">Fe/Cu/Sn</td><td></td></or=dia>	Fe/Cu/Sn					
		Fe/Cu/Sn (>or=Dia 12.5mm)	Cu/Sn (KZ, FG, ES, DB series)	Cu-Zn/Au (KG series type-Ⅲ)				
		Plating thickr Plating type r treatment aft	ness 12µm natte No heat er plating	Plating thickness 10µm Plating type matte No heat treatment after plating	_			
	Resistance to soldering heat	Please refer to page 19 for the recommendation reflow condition.	Correspondence to 260°C flow soldering condition		Not Applicable			
	Solderability Tensile strength			—				
Chromium (VI)	Plating material	naterial Does not contain			Available (Chromium(VI)contained in the plating of fixtures)			
Mercury								
Cadmium		Does not contain						
PBB								
PBDE								
Identification for RoHS compliance parts		Part numbers are changed Add "Pb-free" marking on inner and outer carton label	Part numbers are ch Add "Pb-free" and ' marking on inner an	nanged 'PVCless" id outer carton label.	Part numbers are changed Add "RoHS" marking on outer carton label.			
MSL (IPC/JEDEC J-STD-020D)		Not Applicable						

### ECO-PRODUCTS

## Part Numbering for Pb-free Aluminum Electrolytic Capacitors

#### SMD type

- Part Numbers for Pb-free SMD type capacitors represent as follows: (1) When certain part numbers are changed because of
  - replacement with Pb-free plated terminals, their 11 digit shows the distinction. (Evomple)

(Example)						
1 2 3 4 5 6 7 8 9 10 11 12 13	14					
U 7S 1C 100 M CB 1G	B (Sn-Pb plated terminals)					
U ZS 1C 100 M CL 1G	B (Pb-free plated terminals)					
type Reted Voltage Configuration						
Sorias Codo Rotod Consoltance	BoHS compliant					
Capacitance Tolerance TapingCode(Inclusive case diameter and packing spec)						
L will be put at 11 digit of numbering system						
Execution : <b>* 10th digit</b> of the part number also need to be						
Exception . * for agreet the part number also need to be						
changed for the following series and case size.						
8X6.2 case size of WF. UX and UR : BR to CL						

- \*UE. BC series (Vibration Resistance) is only Pb-free and 11th digit the part number change to "S". \*CD series is only Pb-free. In case of \$12.5 or more:
- 11th digit the part number change to "Q".



E will be put at 10 digit of numbering system



Exception : 10th digit of the part number also need to be changed for the following series and case size. 8X7 case size of SA, SR and SP CA to DD 8X7 case size of ST and SF CH to DD

\*Configuration code is subject to change by series of case diameter.

#### (Example) 9 10 11 12 L <u>NX 2W 221 M SM G</u> ¥ L 2 3 4 5 6 7 8 9 10 11 12 L NX 2W 221 M SE G Type Rated Voltage Case dia Series Code Rated Capacitance Configration Case dia. code Capacitance Tolerance

Screw terminal type

Bracket, Screwbolt, Lock washer (Cr (VI) plating)

Cr (III) plating

RoHS compliant

E will be put at 11 digit of numbering system

### Corresponding to RoHS Directive

		Plastic Film Capacitors					
		Metallized plastic film capacitor XK-(ZH), XK, XP, XT, XL, AK, AP series	Plastic film capacitor for AC Power Based on Applications EC, EN, XH series	Foil type plastic film capacitor YX series			
Corresponding to RoHS Directive		Complied	Complied	Complied			
Material	The portion of the components						
Lead (Pb)	Plating on terminals	Sn plating	Sn plating	Sn plating			
	Internal connection, Internal soldering	Does not contain	Does not contain	Does not contain			
		Fe / Cu / Sn	Fe / Cu / Sn	Fe / Cu / Sn			
	Construction of terminals	Plating thickness 12µm Plating type matte No heat treatment after plating	Plating thickness 3to12µm Plating type matte No heat treatment after plating	Plating thickness 12µm Plating type matte No heat treatment after plating			
	Resistance to soldering heat	Correspondence to 260°c flow soldering condition	Correspondence to 260°c flow soldering condition	Correspondence to 260°c flow soldering condition			
	Solderability Tensile strength	No significant solderability difference between Sn-Ag-Cu and Sn-Pb solder.	No significant solderability difference between Sn-Ag-Cu and Sn-Pb solder.	No significant solderability difference between Sn-Ag-Cu and Sn-Pb solder.			
Chromium (V	(1)						
Mercury		_	Does not contain	Does not contain			
Cadmium		Does not contain					
PBDE							
Identification for RoHS compliance parts		Add "Pb free" marking on inner and outer carton label	Add "Pb free" marking on inner and outer carton label	Add "Pb free" marking on inner and outer carton label			
MSL (IPC/JEDEC J-STD-020D)		Not Applicable	Not Applicable	Not Applicable			